



# AND262RA

# GaAlAs Red Light Emission T-1 Package (3 mm)

#### **Features**

- Double hetero structure die
- Peak wavelength (λp = 660 nm) high bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 10 to 20 mA recommended
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation

### Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	25	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	55	mW
Operating Temperature Range	T <sub>Opr</sub>	-20 to 75	°C
Storage Temperature Range	T <sub>Stg</sub>	-30 to 100	°C

## **Electro-Optical Characteristics (T = 25°C)**

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	-	1.85	2.2	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	-	_	100	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	80	150	_	mcd
Peak Emission Wavelength	l <sub>P</sub>	I <sub>F</sub> = 20 mA	-	660	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	-	25	_	nm
Dominant Wavelength	λd	I <sub>F</sub> = 20 mA	-	640	_	nm
Full Viewing Angle	θ	I <sub>V</sub> = 1/2 Peak	-	70	-	degree

#### Precaution

Please be careful of the following:

- 1. Soldering temperature: 260°C max
  - Soldering time: 3 sec. max
  - Soldering portion of lead: up to 2 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.













